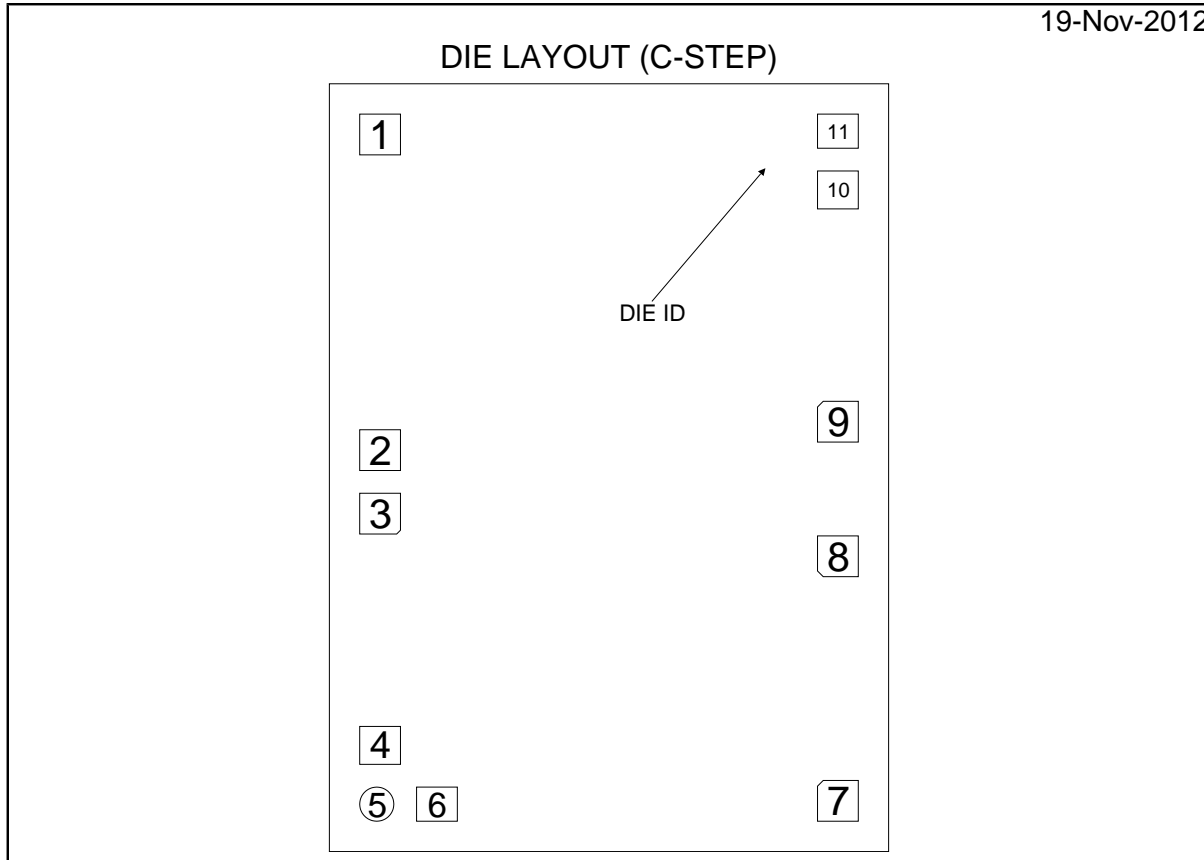


LM319-MDA -MWA
HIGH SPEED DUAL COMPARATOR

19-Nov-2012



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	119C	Bond Pad Opening Size (min)	109.22µm x 91.44µm
Die Step	C	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	152.4mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1498.600µm x 2057.400µm 59.0mils x 81.0mils	Back Side Connection	V-
Thickness	330µm Nominal		
Min Pitch	170.18µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(C-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
Gnd 1	1	-613.41	892.81	109.22	x	109.22
+Input 1	2	-613.41	46.99	109.22	x	109.22
-Input 1	3	-613.41	-123.19	109.22	x	109.22
V-	4	-613.41	-744.22	109.22	x	101.60
NC	5	-622.30	-901.70	91.44	x	91.44
Output 2	6	-461.01	-901.70	109.22	x	91.44
Gnd 2	7	613.41	-892.81	109.22	x	109.22
+Input 2	8	613.41	-237.49	109.22	x	109.22
-Input 2	9	613.41	123.19	109.22	x	109.22
V+	10	613.41	744.22	109.22	x	101.60
Output 1	11	613.41	901.70	109.22	x	91.44

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Notes

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